

# Chip Scale Review

## 2014 Editorial Calendar

### January • February

#### 3D - Wafer-Level Packaging - MEMS

Columns	Technical Features	Trade Show /Conferences
Semiconductor Industry Forecast	Probe Technology Advances	<ul style="list-style-type: none"> <li>• <b>BiTS Workshop</b> Mesa, AZ (March 9-12)</li> <li>• <b>IMAPS Device Packaging (DPC)</b> Fountain Hills, AZ (March 10-13)</li> </ul>
Competitive Strategies and Tactics for the Packaging Industry	Probing $\mu$ -bumps for wide I/O 3D SICs	
Putting 2.5D in Perspective	MEMS Mobile Devices	
Bringing New Electronic Materials to Market	3D IC Stacking	
BGA Socket Systems for Test and Verification	Next-generation TSV Filling by Electroplating	

**R&D Institute Profile**

**Ad Space Close Jan 21 - Ad Materials Deadline Jan 24**

### March • April

#### OSATS – Packaging & Assembly – 3D TSVs

OSATS Market Update	European Assembly and Test	<ul style="list-style-type: none"> <li>• <b>SEMICON China</b> Shanghai China (March 18-20)</li> <li>• <b>APEX Expo</b> Las Vegas, NV (March 25-27)</li> </ul>
IC Packaging Technologies & Trends How the OSATs Stack Up	3D TSV & Heterogeneous Integration	
High-density 2.5D Interposer Market Update	Dispensing Trends	
TSV Reliability Challenges	Glass as a Future Packaging Platform	
	Die & Flip-chip Bonding	
	Semiconductor Packaging Materials	
	Advancements in PoP Technology	

**R&D Institute Profile**

**International Directory of IC Packaging Foundries**

**Ad Space Close Feb 11 - Materials Close Feb 14**

### May • June

#### Materials - Test & Burn-in Sockets - 3D IC Integration

Advanced Packaging Materials Market Update	3DIC & TSV Interconnects	<ul style="list-style-type: none"> <li>• <b>MEPTEC Symposium on Polymers</b> Wilmington, DE (May 6-8)</li> <li>• <b>MEMS Tech Symposium</b> San Jose, CA (May 22)</li> <li>• <b>ECTC</b> Lake Buena Vista, FL (May 27-30)</li> <li>• <b>IEEE/SW Test Workshop (SWTW)</b> San Diego, CA (June 6-11)</li> <li>• <b>SEMICON West</b> San Francisco, CA (July 8-10)</li> </ul>
Standards Update	Enabling Technologies for 2.5D IC/ Si Integration	
Patents Update	3D Integration of SiP	
	High Performance Test Sockets	
	Bond Testing	
	Metrology Trends	
	TSV Interposers	
	Laser Ablation Technology	

**Special Feature: R&D Institute Profile**

**Special Feature: Executive Profile & Perspective**

**Ad Space Close March 28 - Ad Materials Close April 2**

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**July • August**

**Copper Pillar Bumping - Dicing & Singulation - Assembly & Test**

Columns	Technical Features	Trade Show /Conferences
Assembly & Test Market Update	Copper Pillar Bumping	<ul style="list-style-type: none"> <li>• <b>SEMICON Taiwan</b> Taipei, Taiwan (Sept 3-5)</li> <li>• <b>MEPTEC Medical Microelectronics Conference</b> Portland, OR (Sept 18-19)</li> </ul>
Burn in and Test Market Update	Scalable Approaches for 2.5D IC Assembly	
	Cost Reduction of MEMS	
	Bonding/De-Bonding/Wafer-thinning Handling	
	Dicing & Singulation	
	Spring Contact Probes in Wafer Test Applications	
	Solder Trends	

**International Directory of Test and Burn-in Sockets**

**Ad Space Close May 30 - Ad Materials Close Jun 4**

**September • October**

**Thermocompression Bonding – Wafer Probing – Wire Bonding**

Test Trends	TCB for 2.5D/3D Assembly	<ul style="list-style-type: none"> <li>• <b>SMTA International</b> Rosemont, IL (Sept 28-Oct 2)</li> <li>• <b>SEMICON Europa</b> Grenoble, France (Oct 7-9)</li> <li>• <b>IMAPS Microelectronics Symposium</b> San Diego, CA (Oct 13-16)</li> <li>• <b>T-Sensors Summit</b> San Diego, CA (Oct 15-16)</li> <li>• <b>International Test Conference (ITC)</b> Seattle WA (Oct 21-24)</li> <li>• <b>MEMS Executive Congress</b> Scottsdale, AZ (Nov 5-7)</li> <li>• <b>IWLPC-International Wafer-Level Packaging Conference &amp; Exhibition</b> San Jose, CA (Nov 11 -13)</li> </ul>
Patents	3D Packaging Through-glass Vias (TGV)	
	Wafer Probers & Probe Cards	
	High-reliability Wire Bonding	
	Cleaning Processes	
	Automotive Electronic Packaging	

**International Directory of Bonding Equipment for 2.5D and 3D Assembly**  
**Special Feature: Executive Profile & Perspective**

**Ad Space Close Aug 8 - Ad Materials Close Aug 13**

**November • December**

**3D TSVs – Package Test – Inspection**

Advances in Burn-in & Test Sockets	Heterogeneous Integration Through-die Stacking	<ul style="list-style-type: none"> <li>• <b>MEPTEC Packaging, Assembly &amp; Test Conf.</b> Santa Clara, CA (Nov TBD)</li> <li>• <b>SEMICON Japan</b> Tokyo, Japan (Dec 3-5)</li> <li>• <b>RTI 3D ASIP Conference</b> Burlingame, CA (Dec 10-12)</li> <li>• <b>SEMI European 3D TSV Summit</b> Grenoble France (Jan 2015)</li> </ul>
Green Electronics	3D TSVs	
MEMS Industry Report	HVM of 3D ICs	
	Solder Ball Placement	
	Reliable Flip-chip Interconnection	
	Package Inspection	
	Failure Analysis	

**Ad Space Close Oct 10 - Materials Close Oct 15**

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